

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|--|---|------------------|---------|------------------|
| L1 | 17917 | interpos\$4 with (multiple several second other) with (terminal electrode pad landing) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/13 09:57 |
| L2 | 5038 | (chip (integrated adj circuit) semiconductor packag\$3 electronic ic dice die) same 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/13 09:58 |
| L3 | 3811 | (chip (integrated adj circuit) semiconductor packag\$3 electronic ic dice die) with 1 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/13 09:59 |
| L4 | 235 | (bga bump ball flipchip microbump stud) with 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/13 09:59 |